

which the film is attached, and pressing the fluid delivery device against the film to separate the film from the surface of the substrate adjacent to the aperture prior to passing the fluid through the aperture.

3. (Amended) A method according to claim 25, wherein a retaining member is positioned against the film on one side of the aperture to cause the film to detach from the substrate on an opposite side of the aperture.

4. (Amended) A method according to claim 25, wherein the aperture in the substrate is adjacent the edge portion of the first film.

5. (Amended) Apparatus according to claim 18, including a fluid delivery device adapted to be coupled to a pressurised fluid source, the fluid delivery device comprising an outlet adapted to be engaged with an aperture in the substrate to deliver fluid from the pressurised fluid source through the aperture, and the fluid delivery device being movably mounted with respect to the holder between an engaged position, in which the outlet engages with an aperture in a substrate held in the holder in use, and a disengaged position in which the outlet is disengaged from an aperture in a substrate mounted in the holder in use.

15. (Amended) Apparatus according to claim 18, wherein the detachment member is a clamp device comprising two clamp members movable with respect to each other between an open position and a closed position, and the clamp device being

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movably mounted with respect to the holder for movement between a disengaged position, a clamped position and a removed position; whereby, when a substrate is held in the holder in use, the clamp device, with the clamp members in the open position, is moved from the disengaged position to the clamped position, in which the film is located between the clamp members, and when the clamp device is in the clamped position, the clamp members are moved to the closed position to clamp the film between the clamp members, and the clamp device is then moved from the clamped position to the removed position to remove the film from the substrate.

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18. (Amended) Apparatus for detaching a film of material from a surface of a substrate, the apparatus comprising a holder adapted to hold a substrate but not a film attached thereto and the holder holding the substrate in a holding plane, an applicator movably mounted with respect to the holder, and the applicator moving the detachment member into contact with a film of material attached to a substrate held in the holder to apply the detachment member to the film so that the attachment force between the detaching member and the film is greater than the adhesion force between the film and the surface of the substrate, and means for moving the detachment member away from the holding plane to remove the detachment member and the film from a substrate held in the holder.

19. (Amended) Apparatus according to claim 18, wherein the detachment member is an adhesive tape.

20. Apparatus according to claim 19, which includes a supply mechanism comprising a first drum from which the detachment member is unwound for supply to the applicator.

21. (Amended) Apparatus according to claim 18, further comprising a receiving mechanism to receive the detachment member and film removed from the substrate.

22. (Amended) Apparatus according to claim 21, wherein the receiving mechanism comprises a drum on to which the removed detachment member and film is wound.

23. (Amended) Apparatus according to claim 21, wherein the detachment member is continuous between the supply mechanism and the receiving mechanism.

24. (Amended) Apparatus according to claim 15 further comprising a receiving mechanism to receive the detachment member and film removed from the substrate, wherein the moving means is provided by movably mounting one or both of the supply mechanism and the receiving mechanism with respect to the holder.

25. (Amended) A method according to claim 8, including engaging an outlet of a fluid delivery device with an aperture in the substrate from the opposite side of the substrate to the surface to which the film is attached, and causing the fluid delivery

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device to pass a fluid out of the outlet and through the aperture to generate a detaching force between the film of material and the surface of a substrate adjacent to the aperture.

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28. (Amended) A method according to claim 8, wherein the substrate is a substrate for mounting a semiconductor chip thereon.

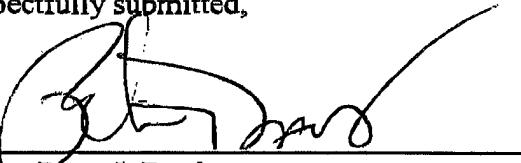
Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "Version With Markings To Show Changes Made".

In the event that the transmittal letter is separated from this document and the Patent and Trademark Office determines that an extension and/or other relief is required, Applicants petition for any required relief including extensions of time and authorizes the Commissioner to charge the cost of such petitions and/or other fees due in connection with the filing of this document to Deposit Account No. 03-1952 referencing 532432000300.

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